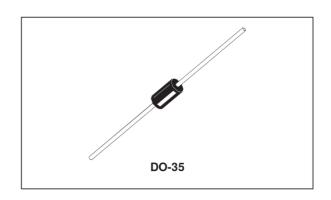


SMALL SIGNAL SCHOTTKY DIODE

DESCRIPTION

Metal to silicon junction diode featuring high breakdown, low turn-on voltage and ultrafast switching. Primarly intended for high level UHF/VHF detection and pulse application with broad dynamic range.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	60	V
I _F	Forward Continuous Current*	15	mA
I _{FSM}	Surge non Repetitive Forward Current*	50	mA
$T_{stg} \ T_{j}$	Storage and Junction Temperature Range	- 65 to 200 - 65 to 200	°C
TL	Maximum Lead Temperature for Soldering dur from Case	230	°C

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
R _{th(j-a)}	Junction-ambient*	400	°C/W

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions			Тур.	Max.	Unit
V_{BR}	$T_{amb} = 25^{\circ}C$	$I_R = 10 \mu A$	60			V
V _F * *	T _{amb} = 25°C	I _F = 1mA			0.41	V
	T _{amb} = 25°C	I _F = 15mA			1	
I _R * *	T _{amb} = 25°C	V _R = 50V			0.2	μΑ

DYNAMIC CHARACTERISTICS

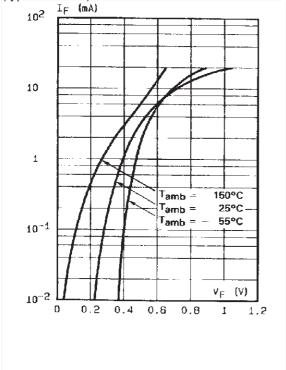
Symbol	Test Conditions			Min.	Тур.	Max.	Unit
С	T _{amb} = 25°C	$V_R = 0V$	f = 1MHz			2.2	рF
τ	T _{amb} = 25°C	$I_F = 5mA$	Krakauer Method			100	ps

^{*} On infinite heatsink with 4mm lead length
** Pulse test: $t_p \le 300 \mu s$ $\delta < 2\%$.

Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.

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Fig. 1: Forward current versus forward voltage (typical values).



1.5

Fig. 2: Capacitance C versus reverse applied

Tamb = 25°C

٧_A (۷)

50

voltage V_R (typical values).

C (pF)

0

10

20

Fig. 3: Reverse current versus ambient temperature.

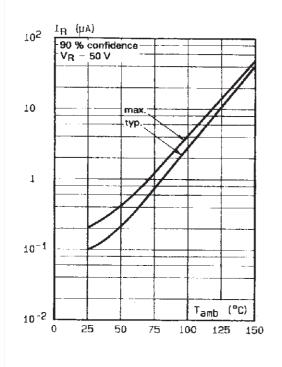
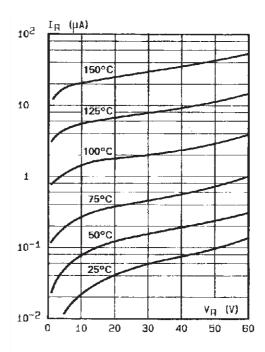


Fig. 4: Reverse current versus continuous reverse voltage (typical values).

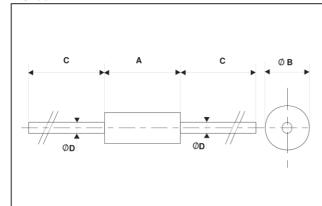
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PACKAGE MECHANICAL DATA

DO-35



REF.	DIMENSIONS				
	Millimeters		Inc	hes	
	Min.	Max.	Min.	Max.	
А	3.05	4.50	0.120	0.177	
В	1.53	2.00	0.060	0.079	
С	28.00		1.102		
D	0.458	0.558	0.018	0.022	

Cooling method: by convection and conduction

Marking: clear, ring at cathode end. Weight: 0.15g

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